

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	21560	multichip or multi adj chip or mcm	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
2	BRS	L2	270473 2	dicing or singulat\$4 or cut\$5 or saw\$4 or laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
3	BRS	L3	1712	1 same 2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
4	BRS	L4	338	1 near4 2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
5	BRS	L6	243	4 and (@ad < "20001222")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	L #	Hits	Search Text	DBs
6	BRS	L7 3	190901	wafer or substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	L8	300589	7 near8 (bond\$4 or solder\$4 or bga or ball near grid or mount\$4 or attach\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	L9	42712	7 near8 (bond\$4 or solder\$4 or bga or ball near grid or mount\$4 or attach\$4) same (encapsulat\$4 or resin or epoxy or infill\$4 or underfill\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	L1 0	8488	9 and 2 and (packag\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
10	BRS	L1 1	1172	9 same 2 same (packag\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	L #	Hits	Search Text	DBs
11	BRS	L1 2	40263	(multiple or many or several or few) near2 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
12	BRS	L1 3	19563	(multiple or many or several or few) adj2 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
13	BRS	L1 4	60	13 same (bond\$4 or solder\$4 or bga or ball near grid or mount\$4 or attach\$4) same 2 same (packag\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
14	BRS	L1 5	51	13 same (bond\$4 or solder\$4 or bga or ball near grid or mount\$4 or attach\$4) same 2 same (package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
15	BRS	L1 6	13	15 and (@ad < "20001222")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	L #	Hits	Search Text	DBs
16	BRS	L ¹ ₇	497	(flipchip or flip adj chip or flip-chip) same (bond\$4 or solder\$4 or bga or ball near grid or mount\$4 or attach\$4) same 2 same (package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
17	BRS	L ¹ ₈	2517	(flipchip or flip adj chip or flip-chip) same (efficien\$4 or throughput or through-put or through adj put or econom\$4 or product\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
18	BRS	L ¹ ₉	217	(flipchip or flip adj chip or flip-chip) same (efficien\$4 or throughput or through-put or through adj put or econom\$4 or product\$) same 2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
19	BRS	L ² ₀	48	17 same (efficien\$4 or throughput or through-put or through adj put or econom\$4 or product\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
20	BRS	L ² ₁	21	20 and (@ad < "20001222")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Type	L #	Hits	Search Text	DBs
21	BRS	L ² ₂	106	19 and (@ad < "20001222")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
22	BRS	L ² ₃	85	22 not 21	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB